PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yun Jing Lin	11/15/2010
Wei-Han Fan	11/11/2010
Yu-Hsien Lin	11/11/2010
Yimin Huang	11/15/2010

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC")	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12951676

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

(512) 867-8528 Phone:

Email: Kim.Reyes@haynesboone.com

Correspondent Name: Haynes and Boone, LLP

Address Line 1: IP Section, 2323 Victory Avenue

Address Line 2: Suite 700

501357931

Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER: 2010-0549 / 24061.1535

NAME OF SUBMITTER: Kelly Gehrke Lyle

PATENT

REEL: 025392 FRAME: 0892

Total Attachments: 3

source=240611535Assignment#page1.tif source=240611535Assignment#page2.tif source=240611535Assignment#page3.tif

> PATENT REEL: 025392 FRAME: 0893

Docket No.: 2010-0549 / 24061.1535

Customer No.: 42717

ASSIGNMENT

WHEREAS,	we.
----------	-----

(1)	Yun Jing Lin	of	16F-2, No. 25, Lane 23, Guandong Road, East District Hsinchu City 300, Taiwan, R.O.C.
(2)	Wei-Han Fan	of	7F, No. 60, Lane 19, Guan-Hsin Road Hsin-Chu City, Taiwan, R.O.C.
(3)	Yu-Hsien Lin	of	20th-2 floor, 68 University Road Hsinchu 300, Taiwan, R.O.C.
(4)	Yimin Huang	of	No. 120 Jinshan 26th Street

have invented certain improvements in

SPACER ELEMENTS FOR SEMICONDUCTOR DEVICE

Hsinchu City 300, Taiwan, R.O.C.

for which we have executed an application for Letters Patent of the United States of America,

<u>X</u>	of even date filed herewith; and filed on a more and assigned application number 29, 676	
	filed of the filed assigned application number 2/951, 676	; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2010-0549 / 24061.1535

Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Yun Jing Lin	
Residence Address:	16F-2, No. 25, Lane 23, Guar Hsinchu City 300, Taiwan, R	ndong Road, East District O.C.
Dated: >0 0/11		Yun Jing Lin Inventor Signature
Inventor Name:	Wei-Han Fan	
Residence Address:	7F, No. 60, Lane 19, Guan-Hs Hsin-Chu City, Taiwan, R.O.	sin Road C.
Dated: >0 (0 '	11'11	Wei-Han Fan Inventor Signature
Inventor Name:	Yu-Hsien Lin	
Residence Address:	20th-2 floor, 68 University Ros Hsinchu 300, Taiwan, R.O.C.	ad
Dated: Yu-Hsi 2010' 1	ien Lin	Yu-Hsien Lin
2010' 1	1' 11'	Inventor Signature

Docket No.: 2010-0549 / 24061.1535

Customer No.: 42717

Inventor Name:

Yimin Huang

Residence Address:

No. 120, Jinshan 26th Street

Hsinchu City 300, Taiwan, R.O.C.

Dated: 1/15/20/0

Inventor Signature

R-1535 (2010-0549) - Assignment 11-9-10 (kgl)

RECORDED: 11/22/2010

Page 3 of 3

PATENT REEL: 025392 FRAME: 0896